

Title (en)
Punching apparatus and punching method

Title (de)
Vorrichtung sowie Verfahren zum Stanzen

Title (fr)
Dispositif ainsi que procédé de poinçonnage

Publication
EP 1101580 A3 20021211 (EN)

Application
EP 00125144 A 20001117

Priority
JP 32712699 A 19991117

Abstract (en)
[origin: EP1101580A2] In a stamping apparatus, a subtracter 22b and an adder 23b compare an output value of an amplifier 29 which is a signal proportional to $\dot{A}T\ddot{U}$ expressing the torque generated at a fulcrum 101 by the reaction force $\ddot{A}F\ddot{U}$ from the material to be stamped 6, to a pulse . duty setting value stored in a pulse . duty setting section 21b, and a signal in which the difference is added to the pulse . duty setting value, is generated, and a switch 25 inputs the signal into a comparator 24b in order to make the signal the comparison signal to the chopping wave outputted from a chopping wave generation circuit 26' in the PWM pulse generation circuit 26. <IMAGE>

IPC 1-7
B26F 1/02; B26F 1/24; B26D 5/00; B26D 5/16; B44B 5/00; B44B 3/00; B26D 5/12

IPC 8 full level
B44B 5/00 (2006.01)

CPC (source: EP)
B44B 5/0066 (2013.01)

Citation (search report)
• [A] DE 3932549 A1 19900405 - ANDO ELECTRIC [JP]
• [PA] EP 0982152 A2 20000301 - ANDO ELECTRIC [JP]
• [A] US 5628673 A 19970513 - MOROOKA MASAYA [JP]
• [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 12 31 October 1998 (1998-10-31)

Cited by
CN105774358A; CN109531690A; CN109986645A; CN104624846A; CN107214364A; CN105774355A; CN107499622A; CN105946419A; CN106182171A; CN108393962A; WO2021046893A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
EP 1101580 A2 20010523; EP 1101580 A3 20021211

DOCDB simple family (application)
EP 00125144 A 20001117